



MULTILAYER CERAMIC CAPACITORS Safety Certified X1/Y2, S2 Series 1808 to 2220 Sizes NP0 & X7R Dielectrics Halogen Free & RoHS Compliance

*Contents in this sheet are subject to change without prior notice.



1. DESCRIPTION

WTC's SAFETY CERTIFIED CAPACITORS are designed for surge or lightning immunity in modem facsimile and other equipments. The capacitors of series S2 are class X1/Y2 compliant respectively.

The green type capacitors in S2 and S3 series are manufactured by using environmentally friendly materials without lead or cadmium.

The terminations are composed of plated nickel and pure tin to feature the superior leaching resistance during soldering.

2. FEATURES

- a. High reliability and stability.
- b. Small size and high capacitance
- c. RoHS compliant
- d. Safety standard approval by EN 60384-14 : 2013 IEC 60384-14 : 2013 UL 60384-14 (Ed 2.0)
- e. Certificate number: TUV: R50381780 UL: E182369
- f. HALOGEN compliant.



3. APPLICATIONS

- a. Modem.
- b. Facsimile.
- c. Telephone.
- d. Other electronic equipment for lighting or surge protection and isolation

Approval Sheet



4. HOW TO ORDER

<u>S2</u>	<u>42</u>	<u>N</u>	<u>100</u>	<u>J</u>	<u>502</u>	<u>C</u>	Ţ
<u>Series</u>	<u>Size</u>	Dielectric	Capacitance	Tolerance	Impulse voltage	Termination	Packaging
S2=X1/Y2 Safety Certified	42 =1808 (4520) 43 =1812 (4532) 52 =2211 (5728) 55 =2220 (5750)	N=NP0 B=X7R	zeros. And R is in place of	D = ±0.5pF F= ±1.0%	is in place of	C= Cu/Ni/Sn E= Soft termination Z= Soft termination + Surface Coating M= Surface Coating	T=7" reeled G=13" reeled

5. EXTERNAL DIMENSIONS & STRUCTURE

5-1 Safety certified Caps.

Size Inch (mm)	L (mm)	W (mm)	T (mm)	M _B (mm)
1808 (4520)	4.50 +0.5/-0.3	2.00±0.25	1.25±0.10 (D)	0.50±0.25
1812 (4532)	4.50 +0.5/-0.3	3.20±0.40	1.40±0.15 (F) 1.60±0.20 (G)	0.50±0.25
2211 (5728)	5.70±0.40	2.80±0.30	2.00±0.20 (K) 2.50±0.30 (M)	0.60±0.30
2220 (5750)	5.70±0.40	5.00±0.40	2.80±0.30 (U)	0.60±0.30

5-2 Safety certified Caps. with soft termination

Size Inch (mm)	L (mm)	W (mm)	T (mm)	M _B (mm)
1808 (4520)	4.50 +0.6/-0.3	2.00±0.30	1.25±0.10 (D)	0.50±0.25
1812 (4532)	4.50 +0.6/-0.3	3.20±0.40	1.40±0.15 (F) 1.60±0.20 (G)	0.50±0.25
2211 (5728)	5.70±0.50	2.80±0.40	2.00±0.20 (K) 2.50±0.30 (M)	0.60±0.30
2220 (5750)	5.70±0.50	5.00±0.50	2.80±0.30 (U)	0.60±0.30

Reflow soldering only is recommended

6. GENERAL ELECTRICAL DATA



Dielectric	NPO NPO	X7R					
Size	1808, 1812, 2211	1808, 1812, 2211, 2220					
Capacitance	3pF to 680pF	100pF to 4700pF					
Capacitance tolerance	Cap.<10pF: C (±0.25pF), D (±0.5pF) Cap.≥10pF: F (±1%), G (±2%), J (±5%), K (±10%), M (±20%)	J (±5%), K (±10%), M (±20%)					
Rated voltage (WVAC)	250	Vac					
Q/ DF(Tan δ)	=Cap<30pF: Q≥400+20C ∾c∈ Cap≥30pF: Q≥1000	DF≤2.5%					
nsulation resistance at Ur	≥100	GΩ					
Peak impulse voltage	5000V ~	- 6000V					
Operating temperature	-55 to +	-125°C					
Capacitance characteristic	±30ppm/℃	±15%					
Termination	Ni/Sn (lead-free	Ni/Sn (lead-free termination)					
Certified number	TUV: R50195920, TUV: R	50381780, UL: E182369					
Test standard	EN 60384-14 : 2013, IEC 60384-	14 : 2013, UL 60384-14 (Ed 2.0)					

2

* NP0: Apply 1.0±0.2Vrms, 1.0MHz±10% for Cap≤1000pF and 1.0±0.2Vrms, 1.0kHz±10% for Cap>1000pF, at 25℃ ambient temperature. * X7R: Apply 1.0±0.2Vrms, 1.0kHz±10%, at 25℃ ambient temperature.

7. PACKAGE DIMENSION AND QUANTITY

C ine		male of	Plasti	c tape
Size	Thickness (mm)/Sy	/mboi	7" reel	13" reel
	1.40±0.15	F	2k	10k
1808 (4520)	1.60±0.20	G	2k	8k
	2.00±0.20	K	1k	6k
	1.25±0.10	D	1k	5k
1812 (4532)	1.60±0.20	G	1k	4k
1012 (4552)	2.00±0.20	К	1k	3k
	2.50±0.30	М	0.5k	3k
	1.60±0.20	G	1k	4k
0044 (EZ00)	2.00±0.20	K	1k	3k
2211 (5728)	2.50±0.30	М	0.5k	3k
	2.80±0.30	U	0.5k	-
2220 (5750)	2.00±0.20	К	1k	3k
2220 (5750)	2.50±0.30	М	0.5k	2k

Unit: pieces

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ASC Safety Certified X1/Y2_(S2)

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8. CAPACITANCE RANGE

	DIELECTRIC					NP0			
	SIZE	180	8	1812	2	2211		221	1
PEAK	IMPULSE VOLTAGE			5000)			600	00
	Contitionted	τυν	UL	τυν	UL	τυν	UL	τυν	UL
	Certificated	IEC60384-14	60384	IEC60384-14	60384	IEC60384-14	60384	IEC60384-14	60384
	3.0pF (3R0)		F						
	3.3pF (3R3)		F						
	3.9pF (3R9)		F						
	4.0pF (4R0)	F	F			К	К	К	K
	4.7pF (4R7)	F	F			K	К	К	K
	5.0pF (5R0)	F	F			К	К	К	К
	5.6pF (5R6)		F			K	К	К	K
	6.0pF (6R0)	F	F			К	К	К	К
	6.8pF (6R8)		F			K	К	K	К
	7.0pF (7R0)		F			K	K	ĸ	K
	8.0pF (8R0)		F			K	K	K	K
	8.2pF (8R2)		F			K	K	K	K
	9.0pF (9R0)		F			K	К	К	K
	10pF (100)	F	F	D	D	K	K	K	K
	12pF (120)		F	D	D	K	K	K	K
	15pF (150)		F	, D	D	K	K	K	K
	18pF (180)		FE	行	1 Stan	K	K	K	K
e	22pF (220)		TEL T	D	- D	K	K	K	K
ů.	27pF (270)	F	τ, F	点腔份		K	K	K	K
Capacitance	33pF (330)		F F A	D		-/_K	K	K	K
apa	39pF (390)	G +	G	D	D	K	K	K	K
ပိ	47pF (470)		G	D	D	K	K	K	K
	56pF (560)		1/\$//G	D	D	Л К	K	K	K
	68pF (680)	G	G		D	K	K	M	M
	82pF (820)		GASS	EVE SOSTEMA	LLIDICE	K -	K	M U	M
	100pF (101)		<u>к</u>	D D	D D		K M	0	U
	120pF (121)	-1.1	K	D	D	M .	M		
	130pF (131)		ĸ	D	D	M	M		
	150pF (151) 160pF (161)		K K	b b b b b		M	M		
	180pF (181)		K	ndog		M	M	├ ────┤	
	220pF (181)		K	101000000000	D K	M	M	├ ────┤	
	220pF (221) 270pF (271)		K	ULOGK CORP	K	M	M		
	300pF (301)		r.	K	K	M	M		
	300pr (301)			۲۱	۲	IVI	IVI		

1. The letter in cell is expressed the symbol of product thickness.

330pF (331)

390pF (391)

470pF (471)

560pF (561)

680pF (681)

720pF (721)

2. For more information about products with special capacitance or other data, please contact WTC local representative.

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Approval Sheet



	DIELECTRIC				'R					
	SIZE	1808		1812		2211		2220		
PEAP	IMPULSE VOLTAGE				50	00				
	Certificated	TUV IEC60384-14	UL 60384	TUV IEC60384-14	UL 60384	TUV IEC60384-14	UL 60384	TUV IEC60384-14	UL 60384	
	100pF (101)	G	G	12000304-14	00304	G	G	12000384-14	00304	
	120pF (121)	G	G			G	G	ł		
	130pF (121)	G	G			G	G			
	150pF (151)	G	G	G	G	G	G			
	160pF (151)	G	G	G	G	G	G	К	К	
	180pF (181)	G	G	G	G	G	G	K	K	
	220pF (221)	G	G	G	G	G	G	K	K	
	270pF (271)	K	K	G	G	G	G	K	K	
	300pF (301)	K	K	G	G	G	G	K	K	
	330pF (331)	K	K	G	G	G	G	K	K	
<i>a</i>	390pF (391)	K	K	G	G	G	G	K	K	
Capacitance	470pF (471)	K	K	G	G	K	K	K	K	
cita	560pF (561)	K	K	G	G	K	K	K	K	
bac	680pF (681)	К	К	K	K	К	K	К	К	
ပီ	720pF (721)	К	К	К	K	К	K	К	К	
	820pF (821)	К	KEL	后K 1	3K	К	K	К	К	
	1,000pF (102)	К	K	М	R'MS	М	М	К	К	
	1,200pF (122)			5昭份;	L V.J	M	М	М	М	
	1,500pF (152)	, N	V szyj		J / Y	M	М	М	М	
	1,800pF (182)	FAIT			- 12 - 12 - 12 - 12 - 12 - 12 - 12 - 12	M	М	М	М	
	2,200pF (222)				$\overline{\nabla}$	М	М	М	М	
	2,700pF (272)		4\$ 1 -			U	U	М	М	
	3,300pF (332)			254				М	М	
	3,900pF (392)		PASSIV	E SYSTEM AL	LIANCE			М	М	
	4,700pF (472)	9	2					М	М	

The letter in cell is expressed the symbol of product thickness.
 For more information about products with special capacitance or other data, please contact WTC local representative.





9. RELIABILITY TEST CONDITIONS AND REQUIREMENTS

No.	Item	Standard Method		Test C	onditio	n				Requiremen	ts	
1.	Visual examination and Dimensions	IEC 60384-1 4.1						* No remar * Dimensio sheet.		efect. onfirm to indiv	idual s	pecification
	Capacitance	IEC 60384-1 4.2.2 IEC 60384-1	* Class I : Cap.≤1000	o.: Room Tem (C0G) 0pF, 1.0±0.2Vr 0pF, 1.0±0.2Vr	ms, 1MI	Hz±10%.		* Capacitance is within specified tolerance. * C_R means rated capacitance for conform to the series of preferred values given in IEC 60063.				
	(Dissipation	4.2.3		•				Dielectric	(Q/D.F.	Rer	nark
	Factor) Tangent of loos angle			Class II : (X7R) .0±0.2Vrms, 1KHz±10%.				Class I (C0G)	Q≥1000 Q≥400+20C		o.≥30pF o.<30pF
								Class II (X	(7R)	D.F.≤2.5%		· ·
		60384-21/22 4.6	T.C. C0G(NP0 X7R	C0G(NP0) -55~125°C at 25°C)	Capacitance Within ±30pp Within ±15%	m/°C	
5.	Voltage proof (Dielectric Strength)	IEC 60384-14 4.2.1	Y Capaci * Duration * The charg * The volta	tor : 1075Vdc tor : 1500Vac. : 60 sec. ge current sha ge shall be rai oltage a rate r	ll not ex sed fron	ceed 0.05 n the near		* No evider test.	nce of c	lamage or flas	sh over	during
6.	Resistance	IEC 60384-21/22 4.5.3	Rated Vol.(V)	Rated Apply Charge Charge					;	Requiremen ≥100GΩ or F		000 Ω-F ,
			>500	500Vdc ≤	50mA	60 sec.	프	Class I (C0G) Class II (X7R)		whichever is ≥10GΩ or R whichever is	xC≥500	Ω-F,
7.	Solderability	IEC 60384-21/22 4.10	* Solder te * Solder te	mperature: 23 mperature: 24 ime : 2±0.5 se	5±5℃(0 5±5℃(1			* 75% min. coverage of all metalized area.				
8.	Resistance	IEC 60384-14	* Solder te	mperature : 26	60±5℃.			Dielectric	I.R.	Cap. Change	е	Q/D.F.
	to Soldering Heat	4.4 IEC 60384-21/22 4.9	* Preheatir immerse	ime : 10±1 sec ng : 120 to 150 the capacitor i ment to be ma	℃ for 1 n a eute	ectic solde	AL ALL	Class I (C0G)	≥1GΩ	Within ±2.5% ±0.25pF, wh is larger		Initiai
		-1.0		ure for 24±2 hi				Class II (X7R)	≥1GΩ	Within ±7.5%	6	requireme nt
9.	Temperature Cycle	IEC 60384-21/22		the five cycles ures and time.		ng to the	•					
		4.11		Temp.(℃)		e(min.)		Dielectric	I.R.	Cap. Cha	ange [C)/D.F.
				Min. operating temp. +0/-3	30±3	3			I.R.	Within ±2	2.5%	1.0(Q) ×
				Room temp.	2~3			Class I (C0G)	To me initial	whicheve	oris li	nitial equirement
			3	Max.operating	30±3	3			requir	llarder		quirement
				temp. +3/-0 Room temp.	2~3			Class II	ment		<	1.5(D.F.) ×

* "Room condition" Temperature: 15 to 35°C, Relative humidity: 25 to 75%, Atmospheric pressure: 86 to 106kPa.



No.	Item	Standard Method	Test Condition		Re	quirements		
10.	Humidity	IEC 60384-14	* Test temp. : 40±2℃.	* No rem	arkable dam	lage.		
	(Damp Heat) Steady State	4.12	* Humidity : 90~95% RH. * Test time : 500 +24/-0hrs. * Applied voltage : 250Vac.	Dielectr ic	I.R.	Cap. Change	Q/D.F.	
			* Measurement to be made after keeping at room temp. for 24±2 hrs (Class I) and 48±4 hrs (Class	Class I (C0G)	≥1GΩ or RxC≥ 25Ω-F,	Within ±3.0% or ±2pF, whichever is larger	≤0.25%	
			II).	Class II (X7R)	whichever is smaller	Within ±15%	≤2.0(D.F.) × initial requireme nt	
11.	Passive Flammability	IEC 60384-14 4.17 IEC 60384-1 4.38	 * Volume sample: 21.56 mm³ * Flame exposure time: 5 sec Max. * Category of flammability : C. 	* Capacitor didn't burn at all.				
12.	Active Flammability	IEC 60384-21/22 4.18	* The capacitors applied UR (250Vac). Then each sample shall be subjected to 20 discharges from a tank capacitor, charge to a voltage that, when discharged, plase Ui 2500V for X1Y2 across the capacitor under test. The interval between successive discharges shall be 5 sec.	* The cheese cloth shall not burn with a flame.				
13.	High Temperature Load (Endurance)	IEC 60384-14 4.14	= 5.0KV (X1Y2 Class Impulse 5KV) & Vp = 6.0KV	* Cap. ch COG with X7R with * D.F. va COG≤0.2 X7R≤5.0 * LR≥1G	anical dama nange : nin ±5% or ±0 iin ±20%. lue : 25%. %. 6Ω.	ge. 0.5pF, whichever i atisfies the specifi	J	
14.	Resistance	IEC	* The middle part of substrate shall be pressurized	* No rem	arkable dam	ade.		
	to Flexure of	60384-21/22	by means of the pressurizing rod at a rate of about	Dielectr		Change		
	Substrate	4.8	1mm per second until the deflection becomes: 1mm for standard termination product, 3mm for soft termination product.	Class I (C0G)	Within larger	1 ±3.0% or ±2pF, w	hichever is	
			20	Class II (X7R)	Withir	1 ±12.5%		
			R = 230 1mm 45 ± 1 45 ± 1 45 ± 1	(This capacitance change means the change of capacitance under specified flexure of substrate from the capacitance measured before the test)			substrate	

* "Room condition" Temperature: 15 to 35°C, Relativ e humidity: 25 to 75%, Atmospheric pressure: 86 to 106kPa.



No.	Item	Standard Method	Test Condition	Requirements
15.	Adhesive Strength of Termination	IEC 60384-21/22 4.15 IEC 60384-1 4.13	* Capacitors mounted on a substrate. A force of 10N applied perpendicular to the place of substrate and parallel the line joining the center of terminations for 10±1 sec. Pressurizing force+ Capacitor+ P.C. Board+	
16.	Vibration	IEC 60384-1 4.17	 * Reflow solder the capacitors on P. C. Board before test. * Vibration frequency : 10~55 Hz/min. * Total amplitude : 1.5mm. * Repeat the conditions for 2 hours each in 3 perpendicular directions. 	* No remarkable damage. * Cap. change and Q/D.F. : To meet initial spec.
17.	Impulse Voltage	IEC 60384-14 4.13	* X1 : 4.0KV * Y2 : 5.0KV. * Number of impulse : 24 max. PASSIVE SYSTEM ALLIANCE	* There shall be no permanent breakdown or flashover.

* "Room condition" Temperature: 15 to 35°C, Relative humidity: 25 to 75%, Atmospheric pressure: 86 to 106kPa.

CHAIGN TECHNOLOG



EMBOSSED TAPE DIMENSIONS



Size	18	08	18	12	22	11	22	20
Chip Thickness	1.25±0.10 1.40±0.15 1.60±0.20	2.00±0.20	1.25±0.10 1.60±0.20 2.00±0.20	2.50±0.30	1.60±0.20 2.00±0.20	2.50±0.30 2.80±0.30	2.00±0.20	2.50±0.30
Ao	<2.50	<2.50	<3.90	<3.90	<3.30	<3.30	<5.80	<5.80
Bo	<5.30	<5.30	<5.30	<5.30	<6.50	<6.50	<6.50	<6.50
Т	0.25±0.10	0.25±0.10	0.25±0.10	0.25±0.10	0.30±0.10	0.30±0.10	0.30±0.10	0.30±0.10
Ko	<2.50	<2.50	<2.50	<3.50	<2.50	3.50	<2.50	<3.50
w	12.0±0.30	12.0±0.30	12.0±0.30	12.0±0.30	12.0±0.30	12.0±0.30	12.0±0.30	12.0±0.30
Po	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10
10xP ₀	40.0±0.20	40.0±0.20	40.00±0.20	40.00±0.20	40.0±0.20	40.0±0.20	40.00±0.20	40.00±0.20
P 1	4.00±0.10	4.00±0.10	8.00±0.10	8.00±0.10	8.00±0.10	8.00±0.10	8.00±0.10	8.00±0.10
P ₂	2.00±0.10	2.00±0.10	2.00±0.10	2.00±0.10	2.00±0.10	2.00±0.10	2.00±0.10	2.00±0.10
Do	1.50+0.10/-0	1.50+0.10/-0	1.50+0.10/-0	1.50+0.10/-0	1.50+0.10/-0	1.50+0.10/-0	1.50+0.10/-0	1.50+0.10/-0
D ₁	1.50±0.10	1.50±0.10	1.50±0.10	1.50±0.10	1.50±0.10	1.50±0.10	1.50±0.10	1.50±0.10
Е	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10
F	5.50±0.10	5.50±0.10	5.50±0.10	5.50±0.10	5.50±0.10	5.50±0.10	5.50±0.10	5.50±0.10

IN Train	101	U 51	
I LI HAIN	Inou	00000	DATION.
-4/////	INCV	CODDI	KHIN.

Size	1808, 1812, 2211, 2220	
Reel size	7"	13"
C	13.0+0.5/-0.2	13.0+0.5/-0.2
W ₁	12.4+2.0/-0	12.4+2.0/-0
A	178.0±1.0	330.0±1.0
N	60.0+1.0/-0	100±1.0

APPLICATION NOTES



Storage

To prevent the damage of solderability of terminations, the following storage conditions are recommended: Indoors under 5 ~ 40°C and 20% ~ 70% RH; MSL Level 1.

No harmful gases containing sulfuric acid, ammonia, hydrogen sulfide or chlorine.

Packaging should not be opened until the capacitors are required for use. If opened, the pack should be re-sealed as soon as is practicable. Taped product should be stored out of direct sunlight, which might promote deterioration in tape or adhesion performance. The product is recommended to be used within 12 months after shipment and checked the solderability before use.

Handling

Chip capacitors are dense, hard, brittle, and abrasive materials. They are liable to suffer mechanical damage, in the form of cracks or chips. Chip Capacitors should be handled with care to avoid contamination or damage. To use vacuum or plastic tweezers to pick up or plastic tweezers is recommended for manual placement. Tape and reeled packages are suitable for automatic pick and placement machine.

Preheat

In order to minimize the risk of thermal shock during soldering, a carefully controlled preheat is required. The rate of preheat should not exceed 3° per secon d.

Soldering

Use middy activated rosin RA and RMA fluxes do not use activated flux. The amount of solder in each solder joint should be controlled to prevent the damage of chip capacitors caused by the stress between solder, chips, and substrate.



* Soldering iron tip diameter ≤1.0 mm and wattage max. 20W.

* The Capacitors shall be pre-heated and that the temperature gradient between the devices and the tip of the soldering iron.

* The required amount of solder shall be melted on the soldering tip.

* The tip of iron should not contact the ceramic body directly.

* The Capacitors shall be cooled gradually at room temperature after soldering.

* Forced air cooling is not allowed.



b.) Reflow soldering :



Cooling

After soldering, cool the chips and the substrate gradually to room temperature. Natural cooling in air is recommended to minimize stress in the solder joint.

Cleaning

All flux residues must be removed by using suitable electronic-grade vapor-cleaning solvents to eliminate contamination that could cause electrolytic surface corrosion. Good results can be obtained by using ultrasonic cleaning of the solvent. The choice of the proper system is depends upon many factors such as component mix, flux, and solder paste and assembly method. The ability of the cleaning system to remove flux residues and contamination from under the chips is very important.

